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Custom IC  
Cadence Design Systems

June 10, 2003

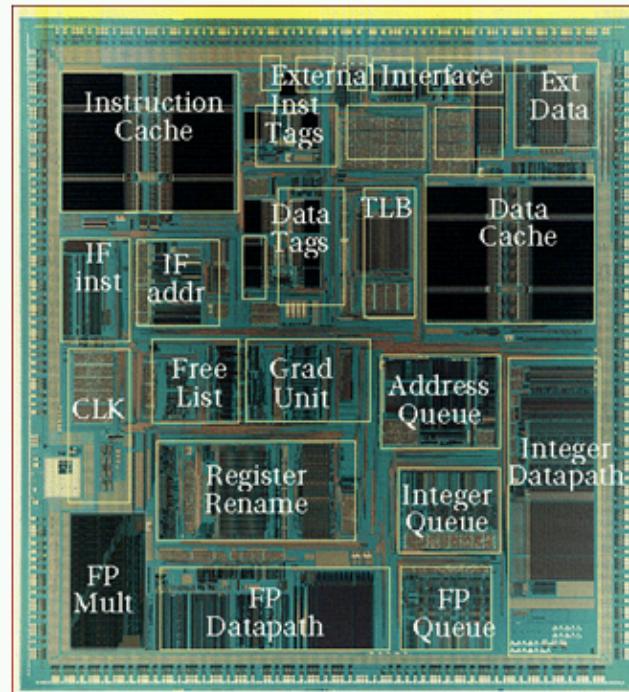
**UltraSim The complete SoC Transistor-level Sign-off solution for Timing, Noise, Power and Reliability**

Are you using an accelerated SPICE simulator?

Polls are closed.



[ Poll A ]



# UltraSim

## The Complete SoC Transistor Level Sign-off Solution for Timing, Noise, Power and Reliability

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## Why Use a Fast Spice Simulator?

- Historical reasons ✓
  - Capacity limitations of SPICE (pre/post layout)
  - Reduction in simulation time
- Mixed signal simulation
  - Digital designs w/ some analog
  - Analog designs w/ some digital
  - Accuracy of A/D, D/A interfaces
  - Missing behavioral models (VerilogA/MS)
- Rapid prototyping ✓
  - Accuracy is close, but not perfect,
    - But neither are the device models
  - Shorten design cycle ✓

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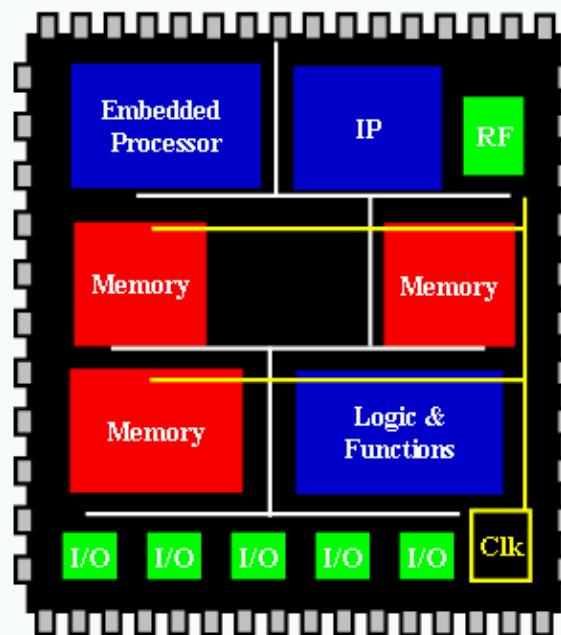
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## Why Use a Fast Spice Simulator?

## Where Does Fast Spice Fit?

- Large digital
  - Verilog / VHDL is not accurate enough.
- Memories
  - Too large to simulate in SPICE
- Mixed signal (PLL's, ADC's, DAC's)
  - Too slow in SPICE due to digital portion
- System on Chip (SoC)
  - No other way without behavior models

## Mixed Signal SoC Verification



- Predominantly digital
- Digital simulation
- Some A / MS blocks
- Analog simulation of individual blocks
- Full chip simulation is difficult, but necessary

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## Mixed Signal SoC Verification

## UltraSim: The Full Chip Simulation Solution

*Hierarchical full-chip transistor-level simulator*

- **Memory, digital & mixed-signal applications**
  - Single pass power, timing, noise & reliability
- **Ultra-high capacity**
  - 10M+ transistor flat
  - 1B++ transistor hierarchical
  - Ideally suited for SoC's and memories
- **Ultra-accurate**
  - SPICE-like (within 1-3%) – timing, pwr, volt.
- **Ultra-high performance (vs SPICE)**
  - 10x to 1,000x faster for flat netlists
  - 1,000x or more for hierarchical netlists
- **Integrations with AMS Designer and ADE**

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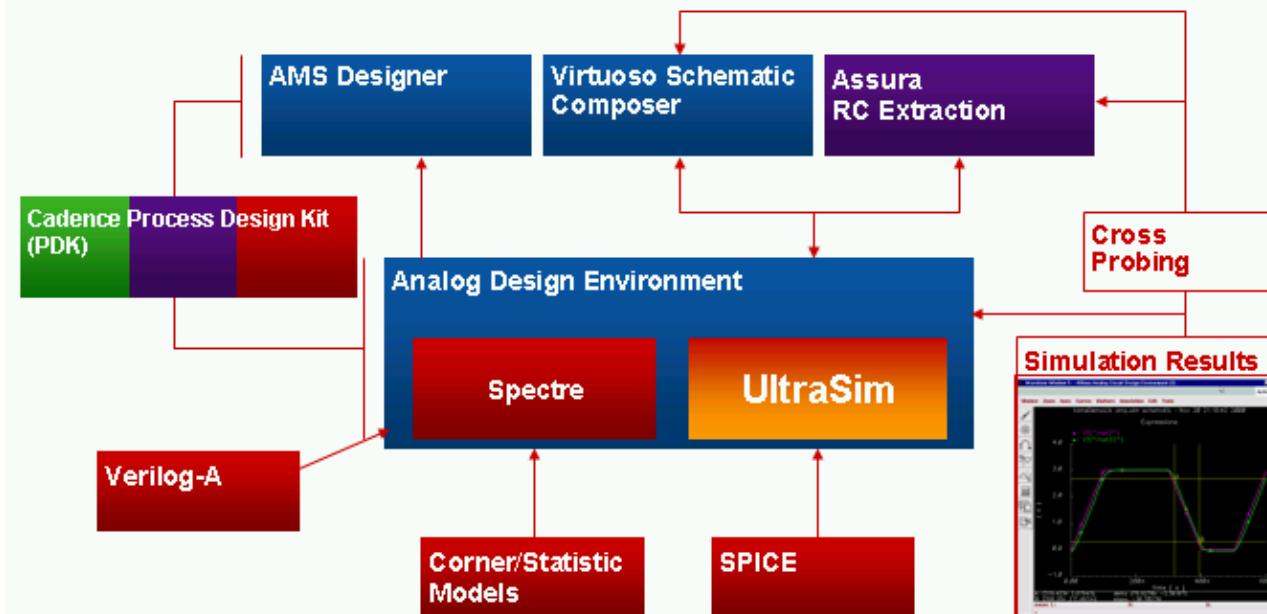
## UltraSim: The Full Chip Simulation Solution

## Complete Set of Analyses

- Reliability analysis
  - Only fast simulator that supports (HCl,NBTI)
  - Critical at 130nm and below
- Timing analysis
- Noise analysis including cross coupling
  - Overshoot & undershoot (Both C and L)
- Power analysis
  - Element & subcircuit level power
  - IR drop (integration w/ VoltageStorm)

## Analog Integrated Circuit (IC) Design Solution

The World's Most Widely Used Solution

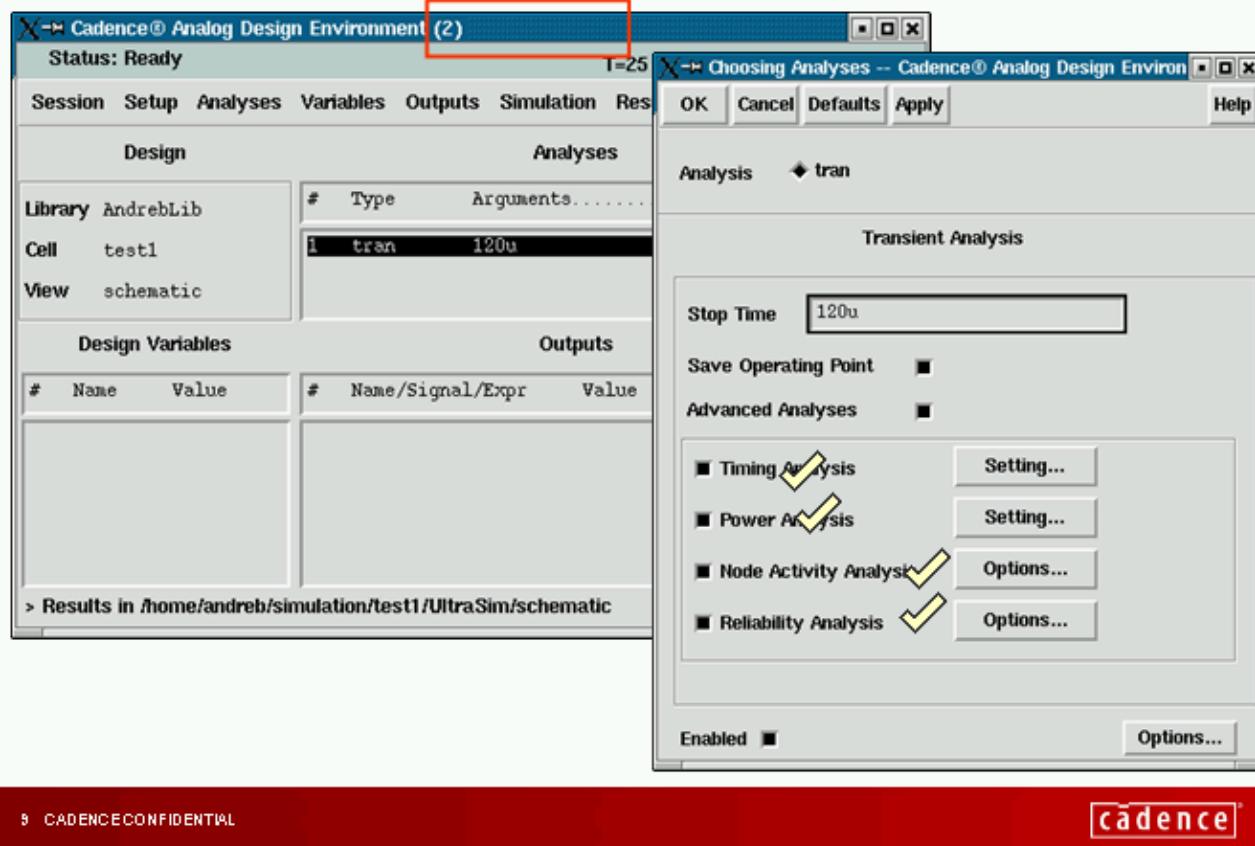


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## UltraSim inside Analog Design Environment (ADE)

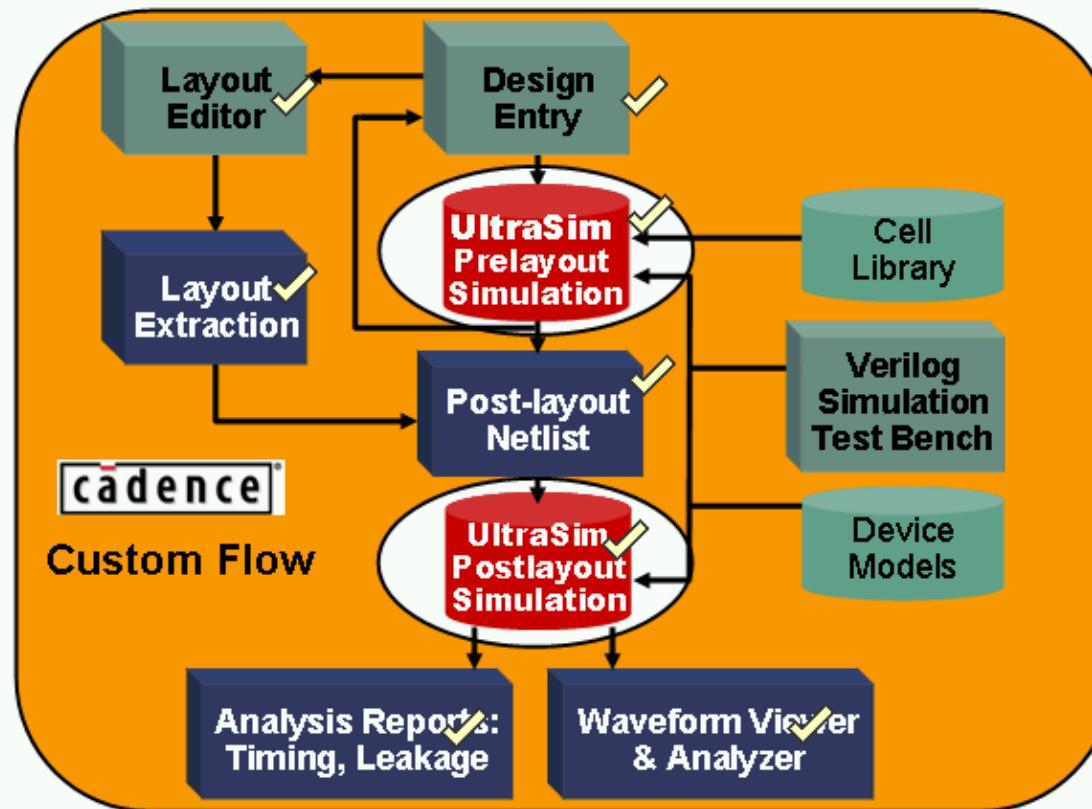


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## UltraSim inside Analog Design Environment (ADE)

## UltraSim in the Custom IC Flow



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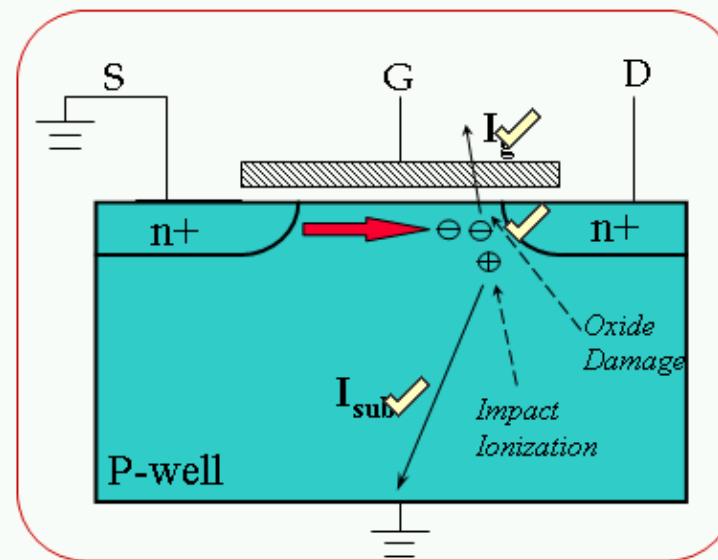
## UltraSim in the Custom IC Flow

## Reliability: A Growing Concern

- HCI and NBTI severely impact design
  - Wasted performance with excessive guard bands
  - Yield reduction due to immediate failures
- Must be addressed with design solution ✓
- The only reliability commercial solutions ✓
  - Cadence offers complete suite of services & tools ✓
  - Device, interconnect, sub-circuit, block to full-chip ✓
  - Experienced team with over 8 years of proven reliability solutions ✓

## Hot Carrier Effects

- $E_{max}$  at drain corner causes hot carrier generation
- Hot carriers cause  $I_{sub}$ ,  $I_{gate}$  and oxide damages



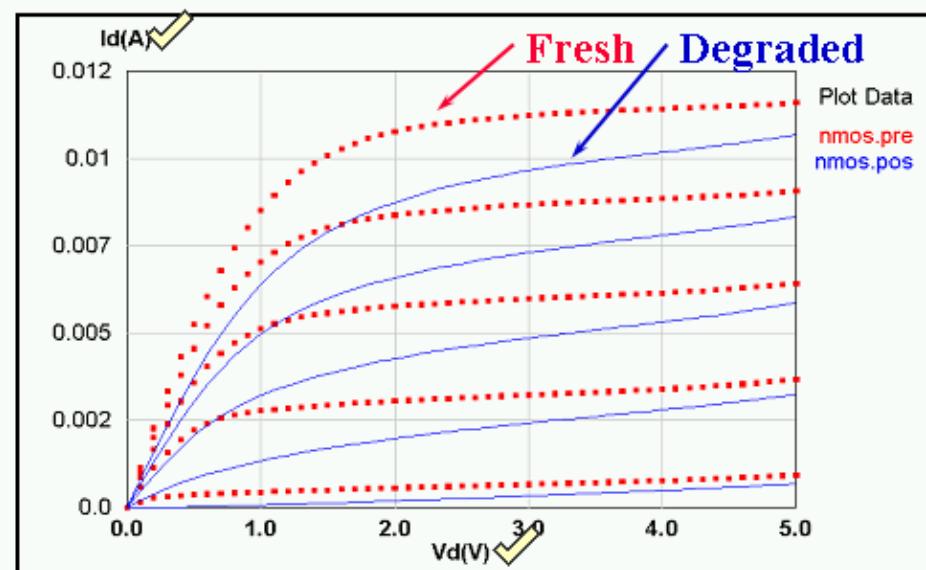
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## Hot Carrier Effects

## Hot Carrier Effects

- Current driving capability degradation
  - Causes longer time delay
  - “Degraded” also sometimes called “aged”



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## Hot Carrier Effects

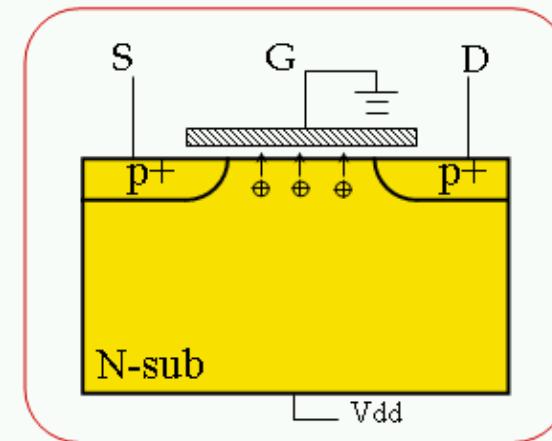
## 0.13μm CMOS Crisis = NBTI

- “Reliability problems scale up as CMOS scales down”

- By David Lammers, EE Times
    - April 12, 2002 (on-line at EETimes.com)
    - April 14, 2002 (EETimes print edition cover story)

- NBTI = Negative Bias Temperature Instability

- Degrades performance & yield of PMOS devices ✓
  - Critical @  $\text{tox} < 50 \text{ angstroms}$  ✓
  - Results in immediate failures ✓
  - Reduces performance ✓



## Degraded Vt

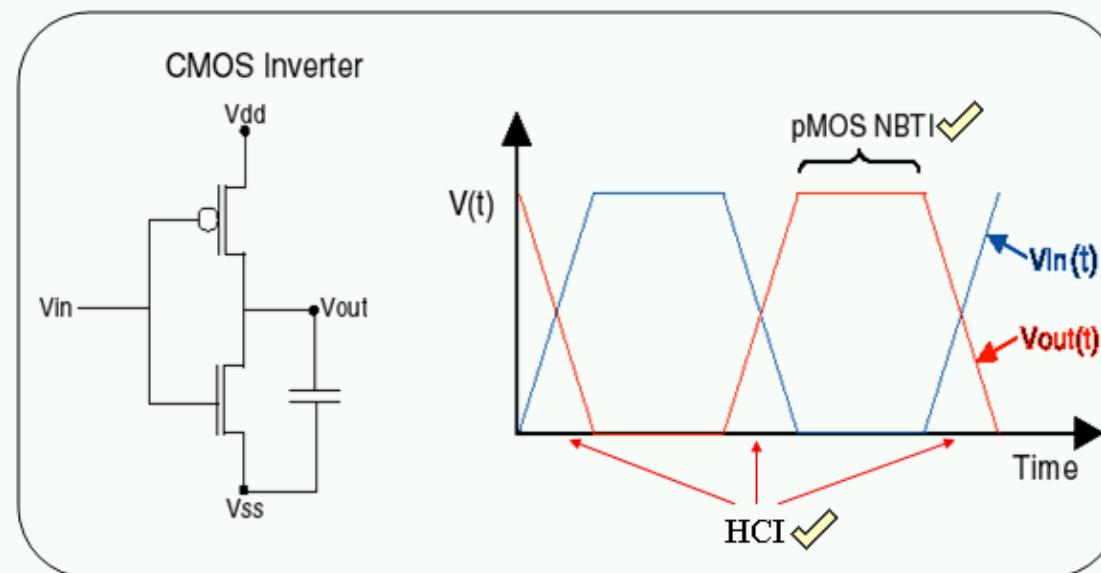


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## Degraded Vt

## HCI & NBTI Effects in Circuit Operation

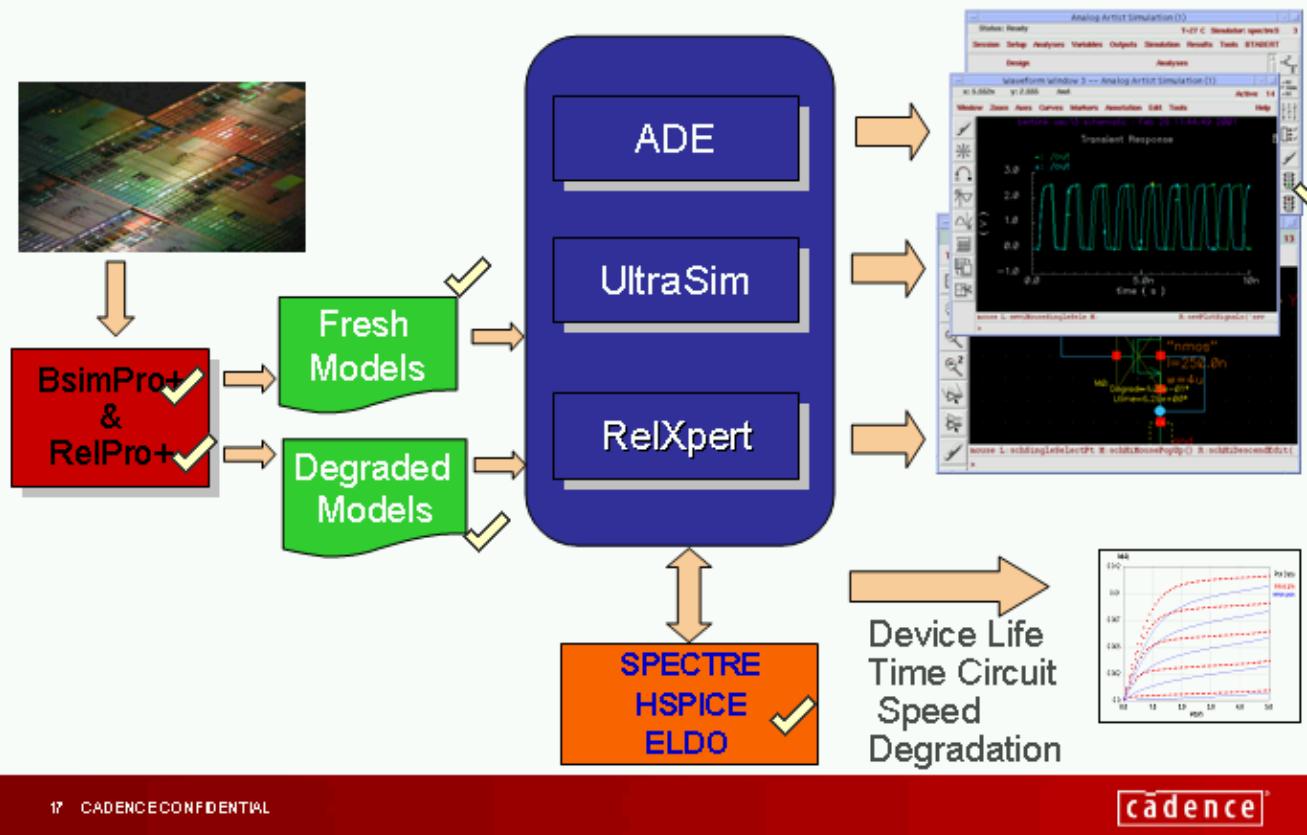


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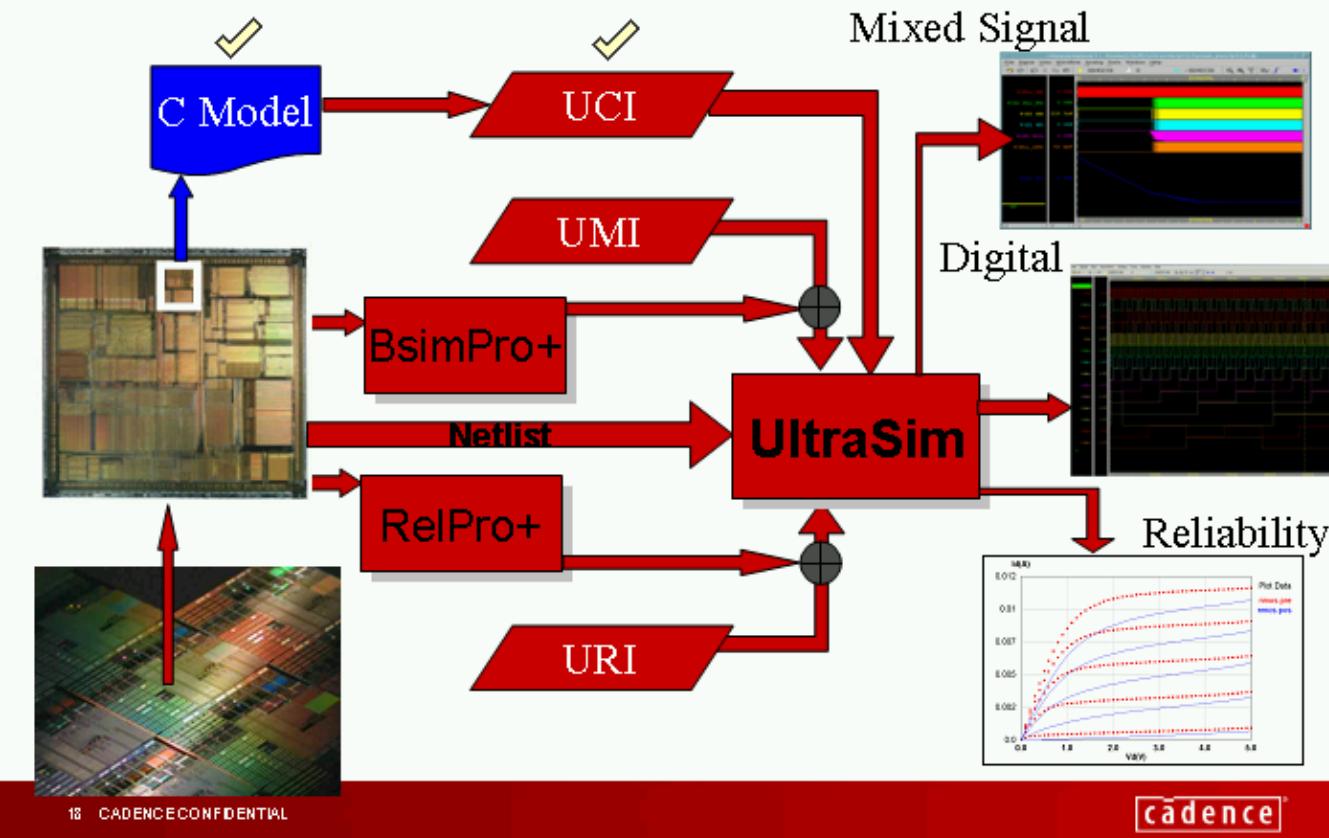
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## HCI & NBTI Effects in Circuit Operation

## Reliability Modeling Flow

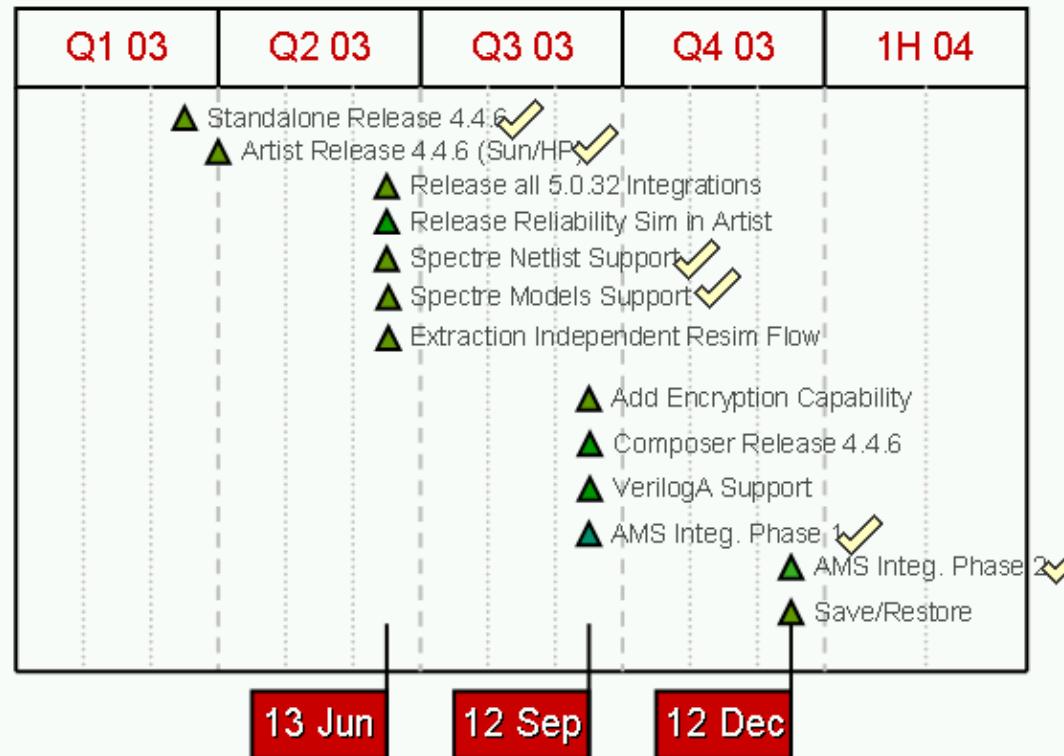


## UltraSim Model/C Interfaces



## UltraSim Model/C Interfaces

## UltraSim Roadmap



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## UltraSim Roadmap

## UltraSim Case Studies

- Mixed Signal Simulation
  - PLL
  - Multiplier
  - ADC / DAC
  - Voltage Regulator
- Digital Simulation
  - Memory
  - Clock Mesh

# UltraSim Simulation Modes Overview

Simulation Mode	df (default) <digital fast mode>	da <digital accurate mode>	ms <mixed signal mode>	a <analog mode>	s <spice mode>	Option
MOSFET	Digital Model		Analog Model		SPICE	
Current / Charge Model	df	da	a		s	mos_methode
Diff. Junct.	df	da	a		-	mosd_methode
DIODE	df	da	a		s	diode_methode
BJT	s					
Accuracy	1    2    3	1    2    3	1    2    3	1    2    3	1    2    3	acc
Default Accuracy (Tol.)	1 (0.01)	2 (0.001)	2 (0.001)	2 (0.001)	2 (0.001)	acc (tol)
	acc=1 -> Relative Tolerance tol=0.01, acc=2 -> tol=0.001, acc=3 -> tol=0.0001					
Netlist Hierarchy	Autodetect (1)				Flat (0)	hier
Partitioning	Digital			Analog	None	
Target Error	< 10%	< 5%	< 1%	< 1%	< 1%	
Application	Functional Verification of Digital Circuits / Memories	Timing Verification of Digital Circuits and Memories, some PLL's, some AMS Designs	PLL's, AMS Designs, special Memories	DAC, ADC, DC/DC, Volt. Refs. Generators		

# UltraSim Simulation Modes Overview

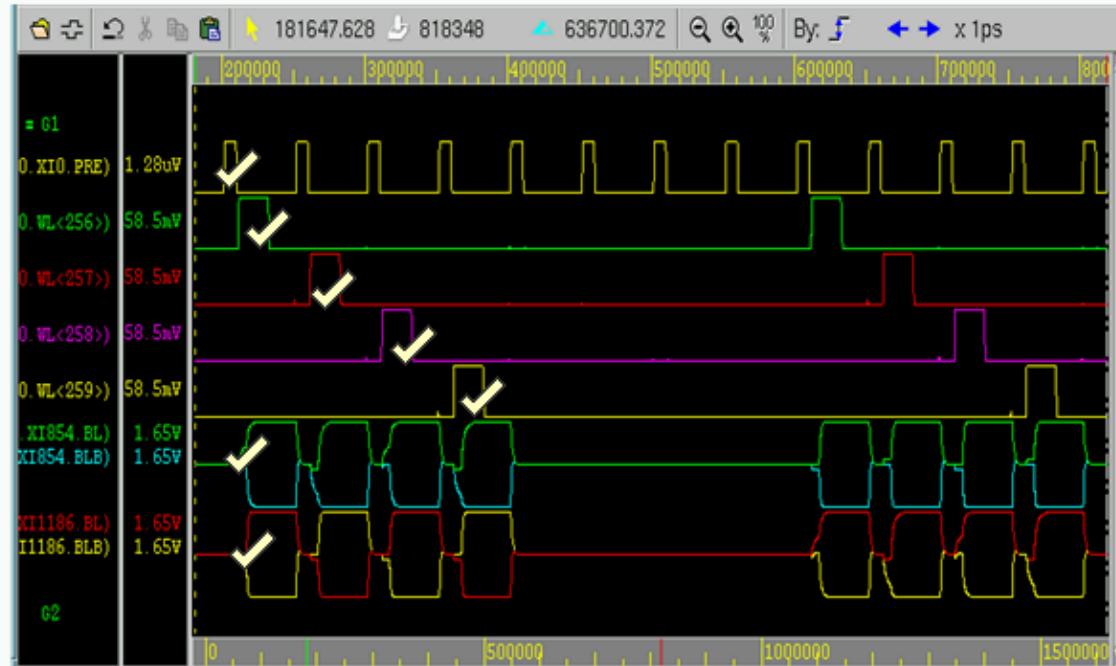
## UltraSim Post-Layout Options

postl	0 (default)	1	2	3	4
RC reduction	no	yes	yes	yes	yes
rcr_fmax (GHz)	1.0	1.0	1.0	1.0	1.0
rshort ( $\Omega$ )	1.0E-6	1.0E-3	0.1	1	100
rvshort ( $\Omega$ )	1.0E-6	1.0E-3	0.1	1	100
cgnd (F)	1.0E-20	1.0E-16	1.0E-16	1.0E-15	1.0E-14
cgnrd	0	0.01	0.1	0.1	0.3

## UltraSim: 3<sup>rd</sup> Generation Technology

- 256K-bit DRAM
  - 308,408 mosfets
  - CPU = 575sec ✓
- 16M-bit DRAM
  - 19,738,112 mosfets
  - CPU = 607sec ✓
- 1G-bit DRAM
  - 1,263,239,168 mosfets
  - CPU = 759sec ✓
- UltraSim performance metric
  - Fast simulation benchmark
- Machine:
  - Solaris2.6, 400MHz CPU
- Number of vectors:
  - 4 write cycles, 4 read cycles

## 1Gb DRAM Simulation Waveform



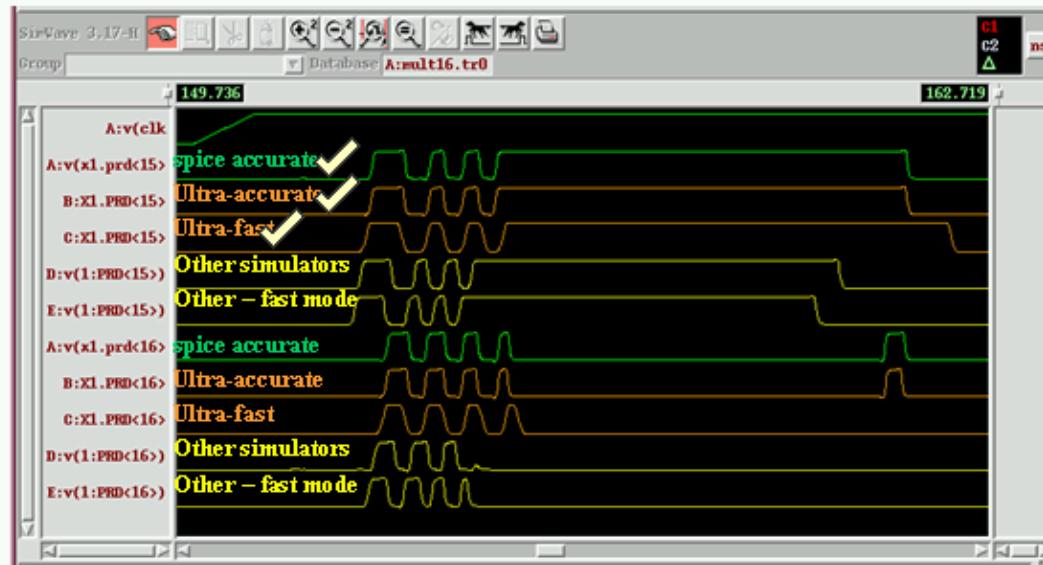
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## 1Gb DRAM Simulation Waveform

## UltraSim: Ultra-fast and Ultra-accurate

- Retains precision even in “fast” mode

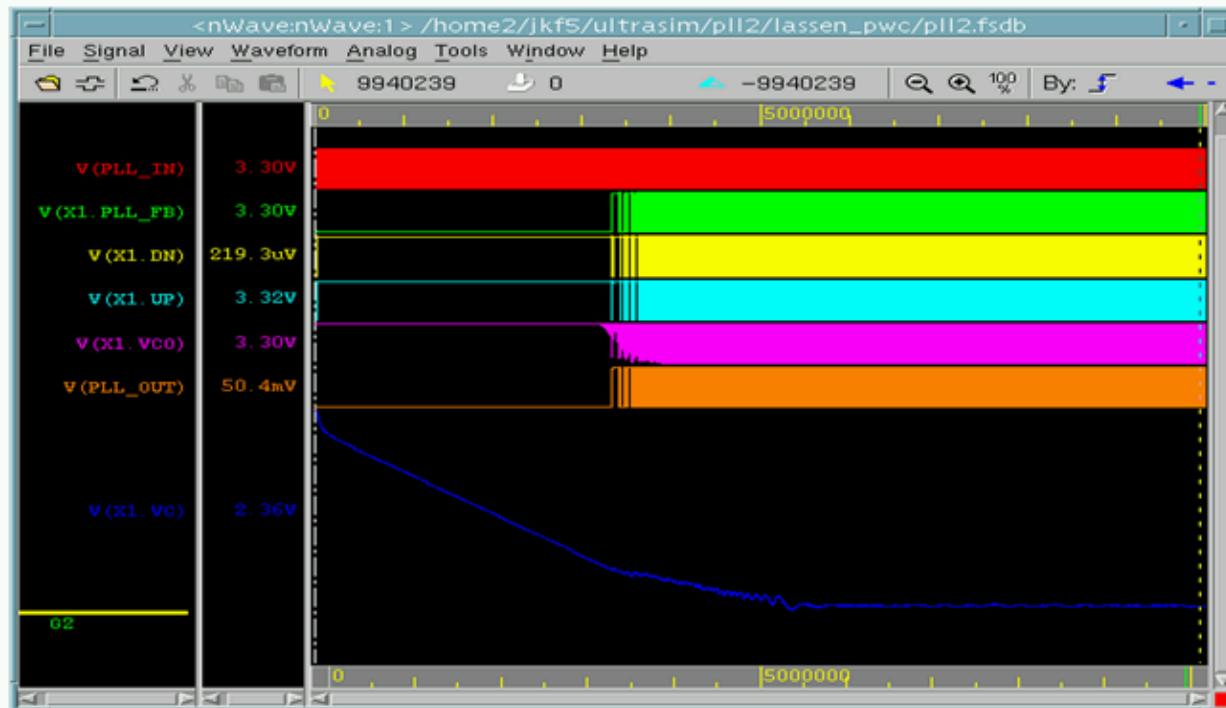


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## UltraSim: Ultra-fast and Ultra-accurate

## PLL Simulation Waveform - Full View

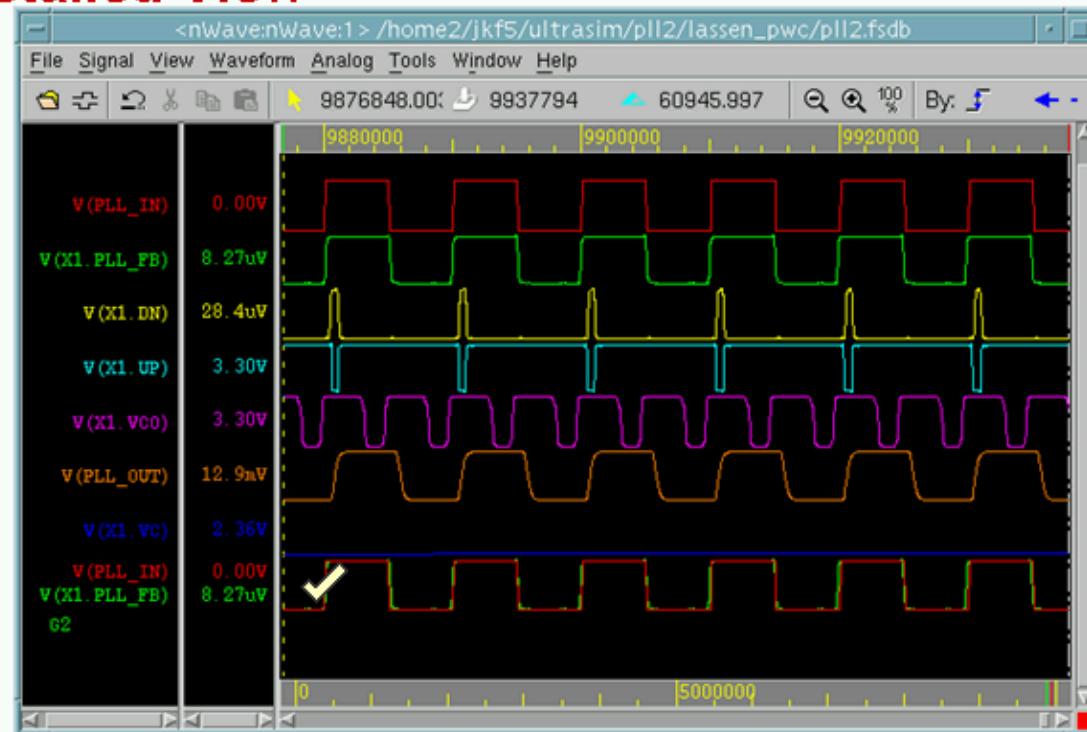


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## PLL Simulation Waveform - Full View

## PLL Simulation Waveform – Detailed View



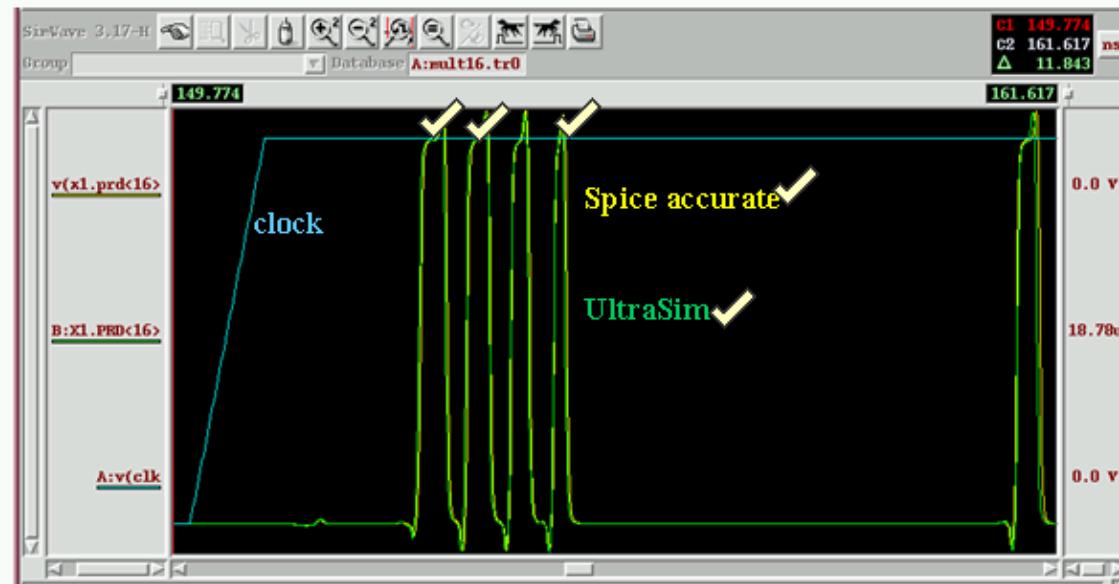
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## PLL Simulation Waveform ? Detailed View

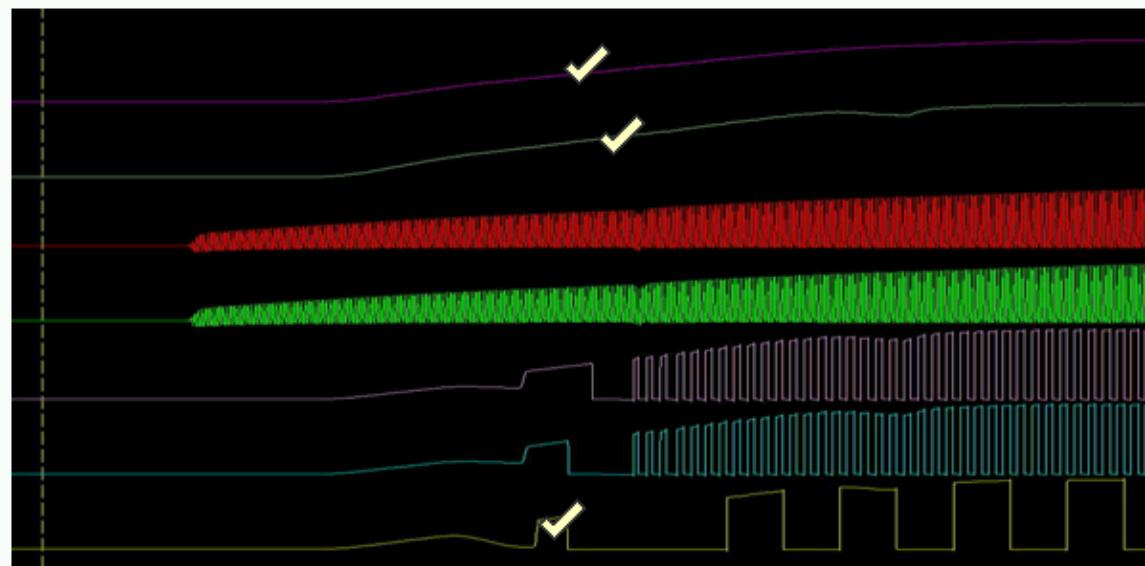
## UltraSim: Accuracy Is Key

- Spice & UltraSim overlaid for a 16bit Multiplier



## Mixed-Signal – Voltage Regulator

- Startup Sequence for Analog Portion



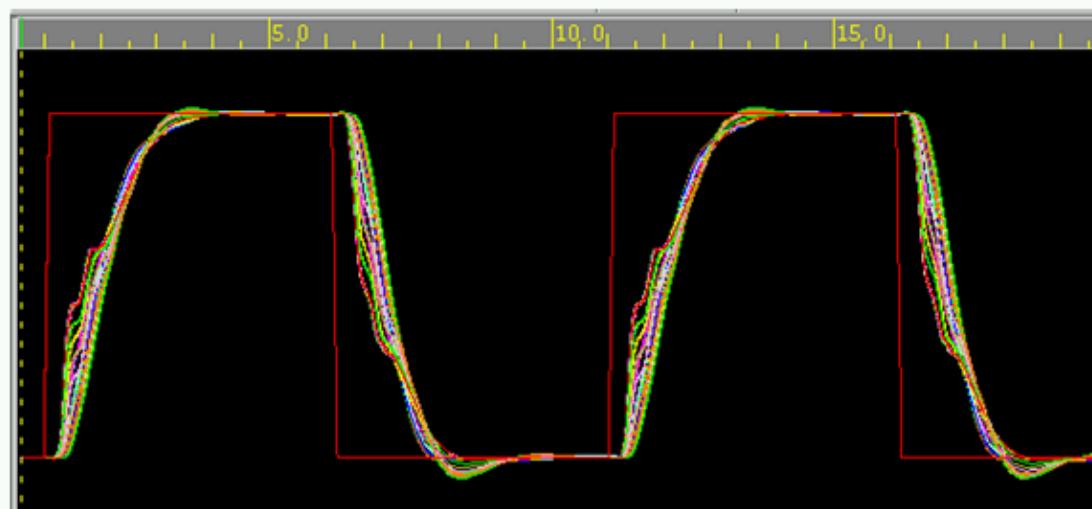
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Mixed-Signal ? Voltage Regulator

## Analysis of Clock Mesh

- Coupling induced noise
  - Capacitive and inductive effects

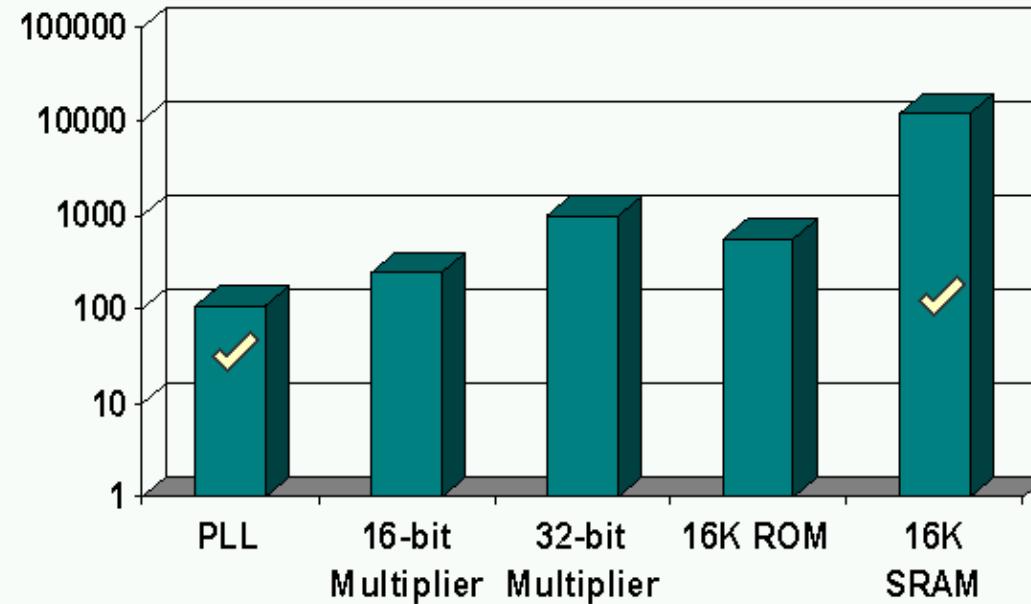


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## Analysis of Clock Mesh

## UltraSim Speed Vs. SPICE



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## UltraSim Speed Vs. SPICE

## Success Stories - Details

Category	Type	# Devices	TRAN Time	Memory Usage	CPU Time
Memories	8M SRAM	25.8M	400ns	110M	96s
	SRAM	50M		443M	1357s
	SRAM (postlayout)	1.1M, 1.1M C	12ns	500M	500s
	SRAM	3.8M	614us	62M	9h
	DRAM	74k	380ns	385M	545s
	256M DRAM	283M	350n	208M	160s
	256M DRAM	586M	500ns	820M	2h 46min
	Flash Memory	35k	2.2us	103M	19 min
Digital Circuits	Digital Design	174k	8ms	213M	7h 35min
	Joystick	15k	22.5m	20M	3.57h
	MCU	45k, 16.8k C	1ms		1.2h
	CLK Tree	15k, 87k C, 71k R	20n	1.5G	25min
	clock mesh	226k, 62k c, 62k r, 60k l	50n	189 MB	40min
	Switch -Capacitor Circuit	271	1ms	19.7M	22min
Mixed-Signal Circuits	PLL	3.1k	8us	14.7M	44min
	Mixed Signal	712	30us	4.4M	142s
	Mixed-Signal Transceiver	25k	200us	137M	7h
	BICMOS Mixed-Signal	8k	10.1us	9M	75 min
	Mouse Controller (MS)	40K, 57k R, 38k C	50ms	137M	3h
SOI	Fire Wire	500k, 30k Diodes, 2k C, 6k R	120u	700M	5 days
	RF ID	42k, 30k Diodes	100us	71M	3.5h
Analog Circuits	Sigma Delta Converter	357	3ms	4M	2.22h
	Bandgap	112	5ms	7.5M	4s
	Op-Amp	78	100us	6.5M	4s
	Bandgap	119	3u	2MB	3s
	Bandpass	1078	1ms	27.5M	40min
	Booster	554	1ms	3.2M	20s
	DC-DC Convertor	602	2.5ms	38M	22min
	ADC	1.6k	6.5us	56M	98min
	ADC	5784	60.5us	60M	48 min

## Success Stories - Details

## Additional UltraSim Details

- Supports industry standard models (partial list)
  - BSM3V3, GP, VBIC95
  - BSIMPD, BSM4, MexHam, HICUM
- Other supported models
  - Only fast simulator to support our High Voltage MOS model (HVMOS) ✓
- Built-in hierarchical RC reduction feature
  - Proven accuracy ✓
- Cadence waveform viewer and hierarchical browser ✓
- SPICE, RelXpert, DSPF, SPEF, VCD & Vector Formats ✓

## UltraSim Availability

- **Supported platforms**
  - SUN Solaris 6.0 or higher (32 or 64 bit)
  - HP-UX 11.0 or higher (32 or 64 bit)
  - Linux—Red Hat 7.2
- **Availability**
  - Last production release—April, 2003
  - Next production release—June 2003 ✓

## What Is the Value of UltraSim?

- Ensuring timing closure
- Prediction of timing error due to interconnect
- Verification of SoC's
  - Simulation capacity for large SoC's
  - Mixed level/mixed signal verification w/ NCsim
  - Unfinished blocks (C macromodel)
- Mixing digital design with analog intellectual property (IP)
  - Digital functional verification of mixed signal
- Rapid prototyping (speed vs. accuracy)
- Improved yield
  - Reducing margin stealing guardbanding
  - Avoiding reliability introduced failures

## Why UltraSim?

- Best capacity, accuracy and performance
  - 3rd generation capacity ✓
  - SPICE-like accuracy
  - Orders of magnitude speed improvement
- Wide range of applications
  - Flat or hierarchical
  - Large digital, memory, SoC, mixed signal,...
  - Pre & post RC extraction with reduction
- The Silicon Accurate Sign-off™ Solution
  - Ensure timing, noise, power & reliability closure
- Performance & time to market

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